

Title (en)
POWER SEMICONDUCTOR MODULE

Title (de)
LEISTUNGSHALBLEITERMODUL

Title (fr)
MODULE A SEMI-CONDUCTEUR DE PUISSANCE

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Application
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Abstract (en)
[origin: DE19950026A1] The invention relates to a power semiconductor module which comprises a stack of carrier substrates that are arranged in layers and one on top of the other and that are provided with at least one strip conductor on at least one main surface. At least one electronic semiconductor component is arranged between two adjacent carrier substrates of the stack. The semiconductor component is electrically contacted to at least one strip conductor of a carrier substrate that is arranged in the stack over the semiconductor component and to at least one additional strip conductor of a carrier substrate that is arranged in the stack under the semiconductor component and in such a way that heat is conducted. The aim of the invention is to provide improved heat emission and a construction that is as compact as possible at the same time. To this end, the two outer carrier substrates of the stack are configured as an upper and a lower wall of a closed housing component which surrounds the at least one semiconductor component. The gaps between the stacked carrier substrates are sealingly closed by means of a circulating wall that is fixed to the carrier substrates.

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